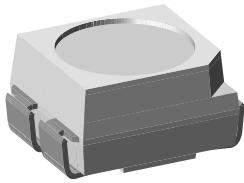


Power SMD LED PLCC-4



19210_1



e3

FEATURES

- High efficient INGaN technology
- Available in 8 mm tape
- Luminous intensity, color and forward voltage categorized per packing unit
- Luminous intensity ratio per packing unit $I_{V_{max.}}/I_{V_{min.}} \leq 1.6$
- ESD class 1
- Suitable for all soldering methods according to CECC
- Lead (Pb)-free device
- Preconditioning: according to JEDEC level 2a

DESCRIPTION

The VLMW32.. white LED is an advanced product in terms of heat dissipation.

The leadframe profile of this PLCC-4 SMD package is optimized to reduce the thermal resistance.

This allows higher drive current and doubles the light output compared to Vishay's high intensity SMD LED in PLCC-2 standard package.

APPLICATIONS

- Interior and exterior lighting
- Indicator and backlighting purposes for audio, video, LCD's switches, symbols, illuminated advertising etc.
- Illumination purpose, alternative to incandescent lamps
- General use

PRODUCT GROUP AND PACKAGE DATA

- Product group: LED
- Package: SMD PLCC-4
- Product series: power
- Angle of half intensity: $\pm 60^\circ$

PARTS TABLE

PART	COLOR, LUMINOUS INTENSITY	TECHNOLOGY WAVELENGTH
VLMW3200-GS08	White, $I_V \geq 560$ mcd (typ 900 mcd)	INGaN/TAG in SiC
VLMW3201-GS08	White, $I_V \geq 710$ mcd	INGaN/TAG in SiC

VLMW320.

Vishay Semiconductors



ABSOLUTE MAXIMUM RATINGS ¹⁾ VLMW320.

PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
Reverse voltage ²⁾		V _R	5	V
DC Forward current	T _{amb} ≤ 65 °C	I _F	30	mA
Surge forward current	t _p ≤ 10 µs	I _{FSM}	0.1	A
Power dissipation		P _V	127	mW
Junction temperature		T _j	100	°C
Operating temperature range		T _{amb}	- 40 to + 100	°C
Storage temperature range		T _{stg}	- 40 to + 100	°C
Soldering temperature	t ≤ 5 s	T _{sd}	260	°C
Thermal resistance junction/ambient	mounted on PC board (pad design see page 6)	R _{thJA}	270	K/W

Note:

1) T_{amb} = 25 °C, unless otherwise specified

2) Driving the LED in reverse direction is suitable for a short term application

OPTICAL AND ELECTRICAL CHARACTERISTICS ¹⁾ VLMW320., WHITE

PARAMETER	TEST CONDITION	PART	SYMBOL	MIN.	TYP.	MAX.	UNIT
Luminous intensity ²⁾	I _F = 30 mA	VLMW3200	I _V	560			mcd
		VLMW3201	I _V	710	900		mcd
Chromaticity coordinate x, y acc. to CIE 1931	I _F = 30 mA	VLMW320.	x y		0.33 0.33		
Angle of half intensity	I _F = 30 mA		φ		± 60		deg
Forward voltage	I _F = 30 mA		V _F		3.7	4.2	V
Reverse voltage	I _R = 10 µA		V _R	5			V
Temperature coefficient of V _F	I _F = 20 mA		TC _{VF}		- 4		mV/K
Temperature coefficient of I _V	I _F = 20 mA		TC _{IV}		- 0.5		%/K

Note:

1) T_{amb} = 25 °C, unless otherwise specified

2) In one Packing Unit I_{Vmax}/I_{Vmin.} ≤ 1.6

LUMINOUS INTENSITY CLASSIFICATION

GROUP	LIGHT INTENSITY (mcd)	
STANDARD	MIN.	MAX.
U2	560	710
V1	710	900
V2	900	1120
AA	1120	1400
AB	1400	1800
BA	1800	2240
BB	2240	2800

CROSSING TABLE

VISHAY	OSRAM	NICHIA
VLMW3200	LWE67C-U2V2	NSCW021T
VLMW3201	LWE67C-V1V2	NSCW021T

Note:

Luminous intensity is tested at a current pulse duration of 25 ms and an accuracy of ± 11 %.

The above type numbers represent the order groups which include only a few brightness groups. Only one group will be shipped on each reel (there will be no mixing of two groups on each reel).

In order to ensure availability, single brightness groups will not be orderable.

In a similar manner for colors where wavelength groups are measured and binned, single wavelength groups will be shipped on any one reel.

In order to ensure availability, single wavelength groups will not be orderable.

CHROMATICITY COORDINATED GROUPS FOR WHITE SMD LED					
	X	Y		X	Y
5L	0.291	0.268	7L	0.330	0.330
	0.285	0.279		0.330	0.347
	0.307	0.312		0.347	0.371
	0.310	0.297		0.345	0.352
5K	0.296	0.259	7K	0.330	0.310
	0.291	0.268		0.330	0.330
	0.310	0.297		0.338	0.342
	0.313	0.284		0.352	0.344
6L	0.310	0.297	8L	0.345	0.352
	0.307	0.312		0.347	0.371
	0.330	0.347		0.367	0.401
	0.330	0.330		0.364	0.380
6K	0.313	0.284	8K	0.352	0.344
	0.310	0.297		0.338	0.342
	0.330	0.330		0.364	0.380
	0.330	0.310		0.360	0.357

Note:

Chromaticity coordinate groups are tested at a current pulse direction of 25 ms and a tolerance of ± 0.01 .

TYPICAL CHARACTERISTICS

$T_{amb} = 25^{\circ}C$, unless otherwise specified

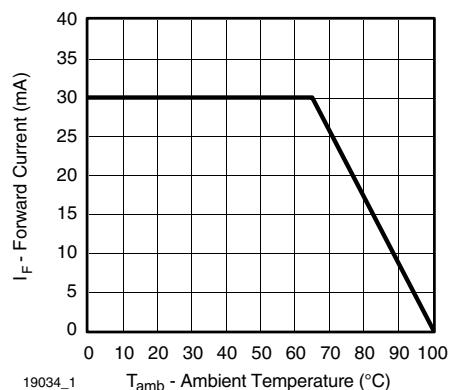


Figure 1. Forward Current vs. Ambient Temperature

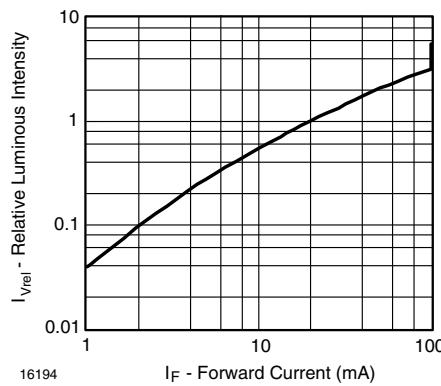
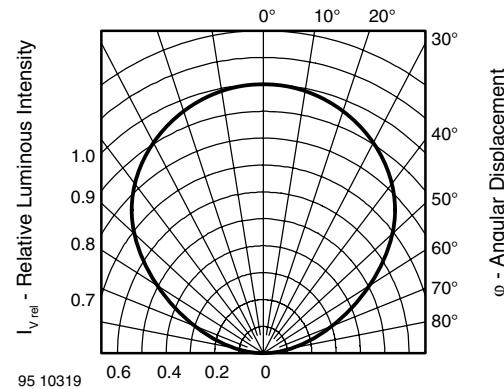
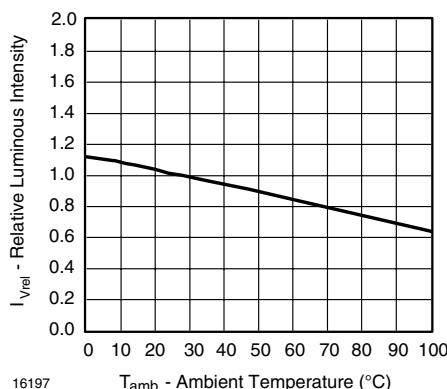
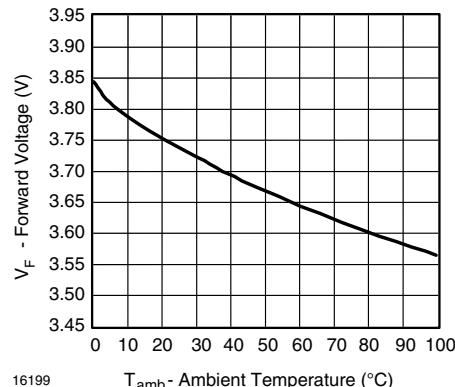
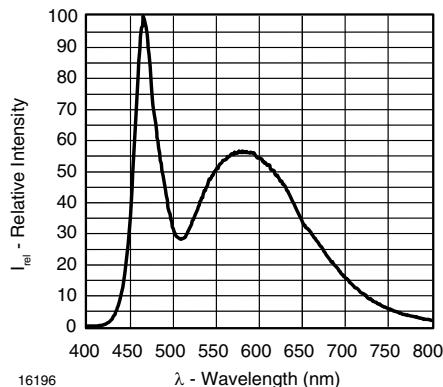
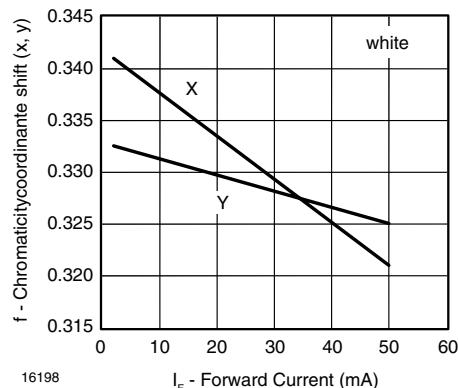
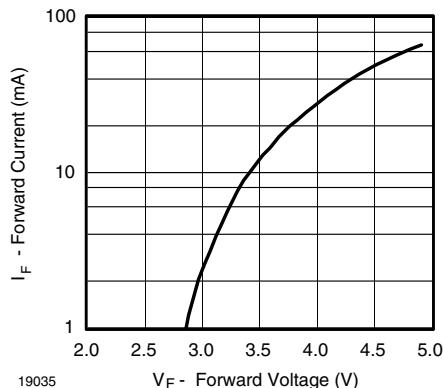
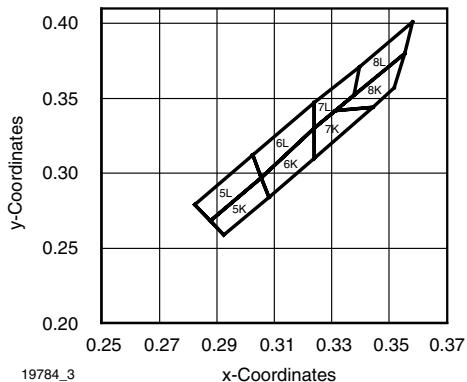


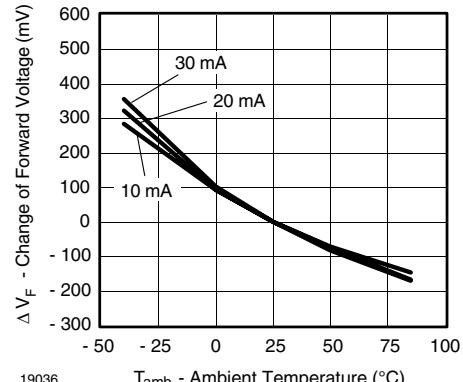
Figure 2. Relative Luminous Intensity vs. Forward Current





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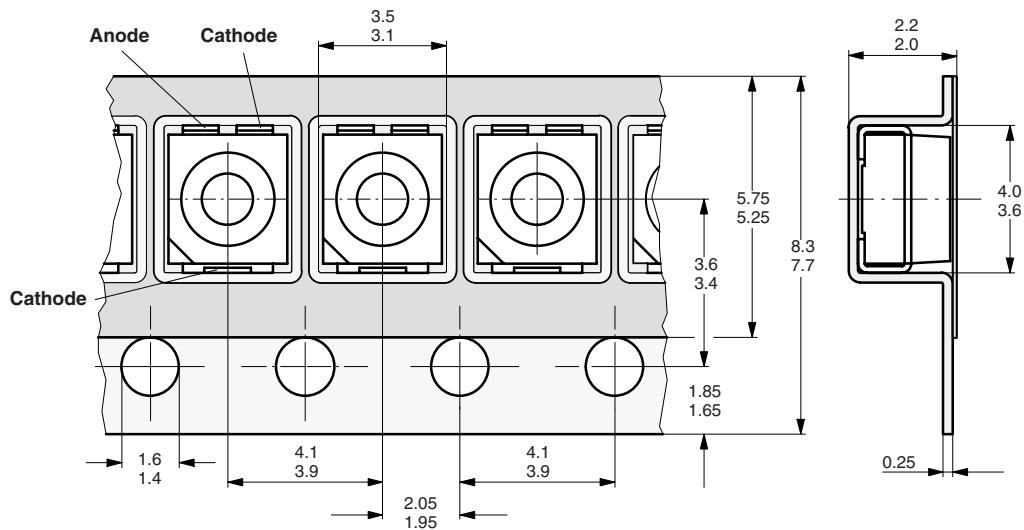
Figure 9. White Grouping SMD



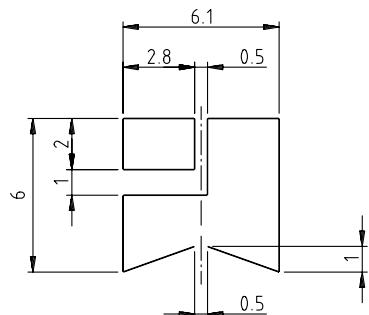
19036

T_{amb} - Ambient Temperature (°C)

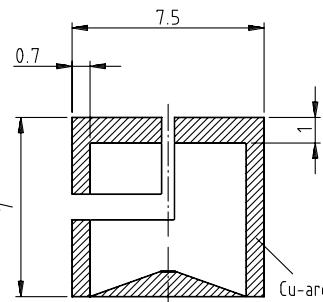
Figure 10. Change of Forward Voltage vs. Ambient Temperature

TAPING Dimensions in millimeters


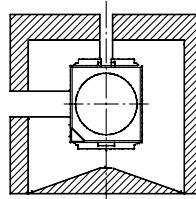
18596

RECOMMENDED PAD DESIGN Dimensions in millimeters(Wave-soldering), $R_{THJA} = 270 \text{ K/W}$ 

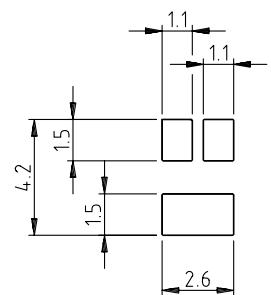
Pad design for improved head dissipation

 solder resist


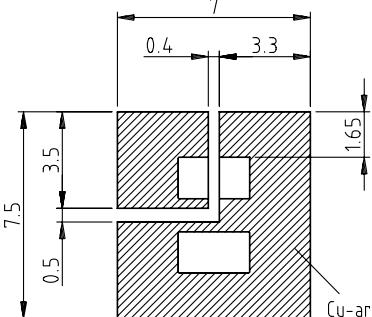
Component location on pad



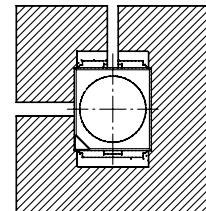
16260

RECOMMENDED PAD DESIGN Dimensions in millimeters(Reflow-soldering), $R_{THJA} = 270 \text{ K/W}$ 

Pad design for improved head dissipation

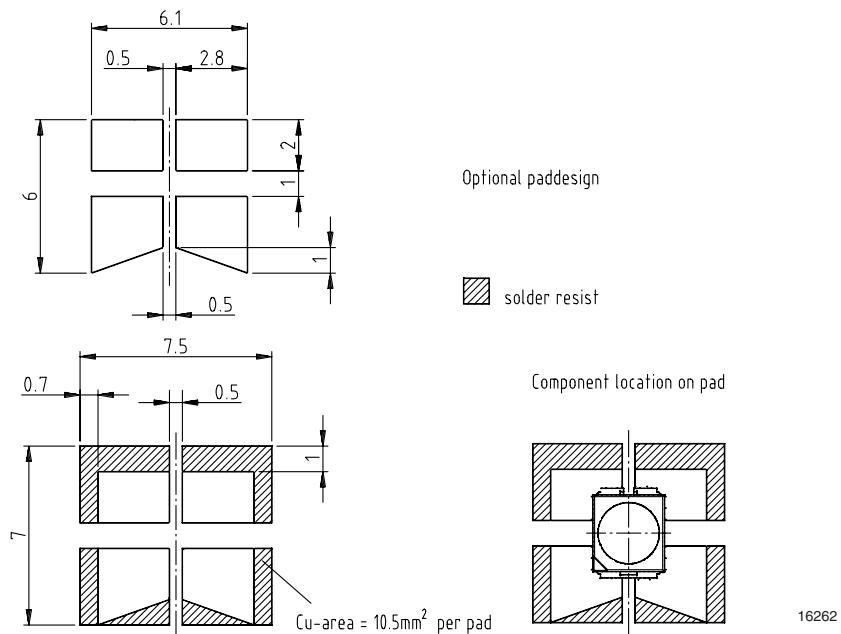
 solder resist


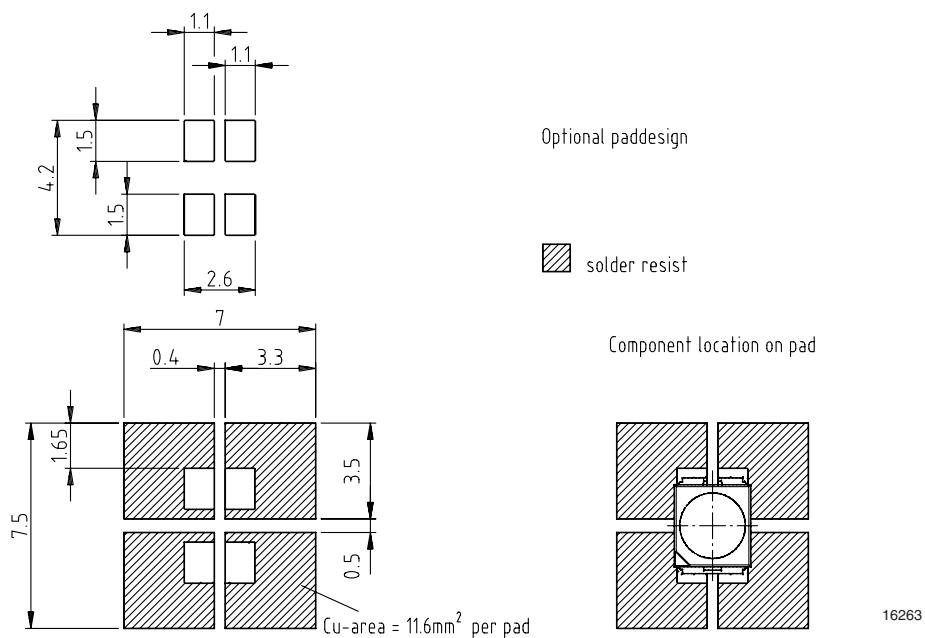
Component location on pad



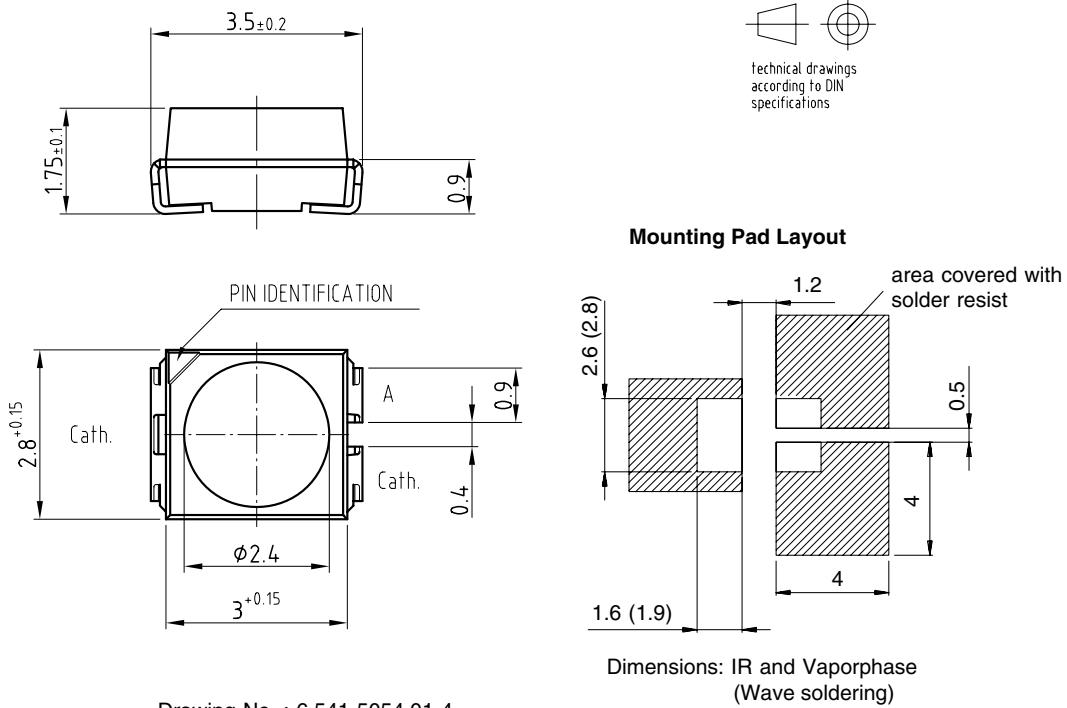
16261

OPTIONAL PAD DESIGN Dimensions in millimeters

(Wave-soldering), $R_{THJA} = 290 \text{ K/W}$

OPTIONAL PAD DESIGN Dimensions in millimeters

(Reflow-soldering), $R_{THJA} = 290 \text{ K/W}$


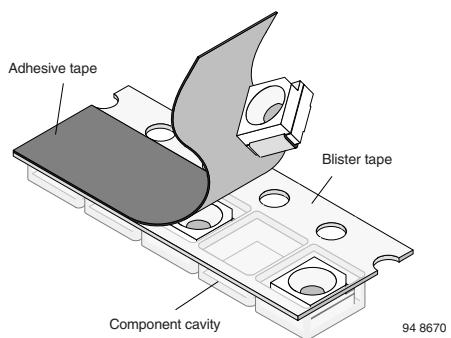
PACKAGE DIMENSIONS in millimeters



METHOD OF TAPING/POLARITY AND TAPE AND REEL

SMD LED (VLM.3-SERIES)

Vishay's LEDs in SMD packages are available in an antistatic 8 mm blister tape (in accordance with DIN IEC 40 (CO) 564) for automatic component insertion. The blister tape is a plastic strip with impressed component cavities, covered by a top tape.



TAPING OF VLM.3...

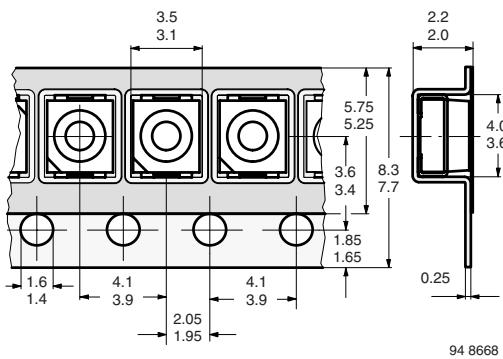


Figure 11. Tape Dimensions in mm for PLCC-2

**REEL PACKAGE DIMENSION IN MILLIMETERS
FOR SMD LEDs, TAPE OPTION GS08
(= 1500 PCS.)**

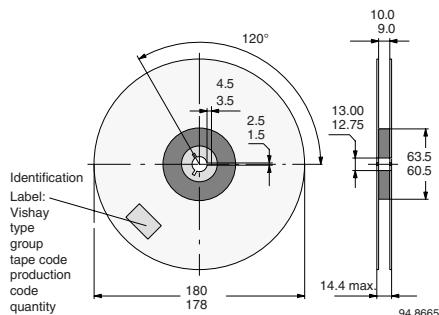
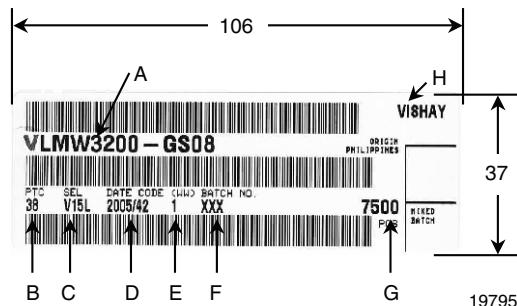


Figure 12. Reel Dimensions - GS08

**BAR CODE PRODUCT LABEL
EXAMPLE:**



SOLDERING PROFILE

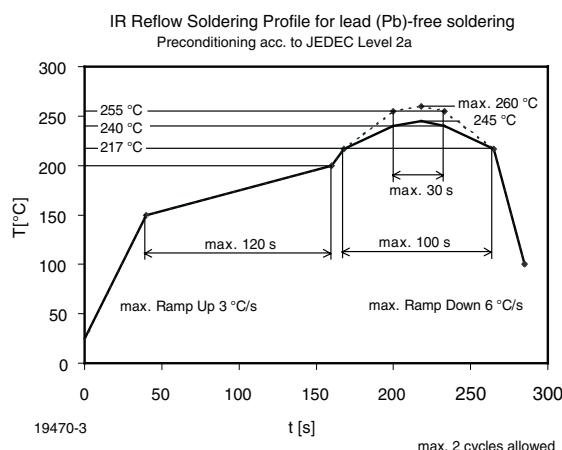


Figure 13. Vishay Lead (Pb)-free Reflow Soldering Profile
(acc. to J-STD-020C)

- A) Type of component
- B) Manufacturing plant
- C) SEL - selection code (bin):
e.g.: V1 = code for luminous intensity group
5L = code for chrom. coordinate group
- D) Date code year/week
- E) Day code (e. g. 1: Monday)
- F) Batch no.
- G) Total quantity
- H) Company code

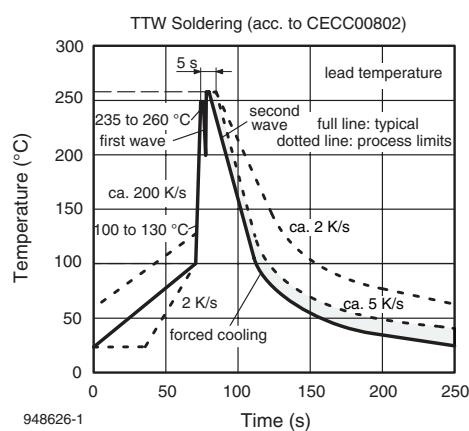
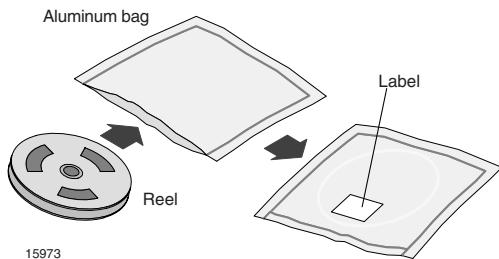


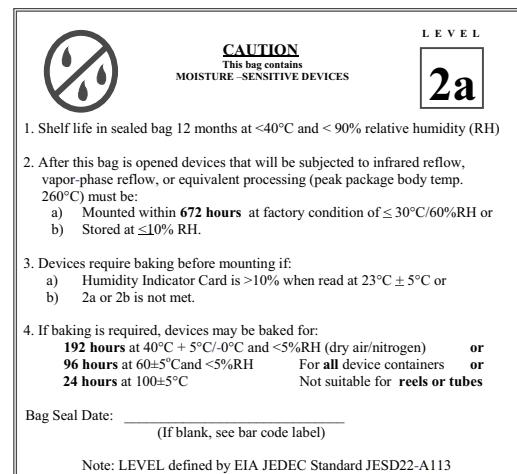
Figure 14. Double Wave Soldering of Opto Devices (all Packages)

DRY PACKING

The reel is packed in an anti-humidity bag to protect the devices from absorbing moisture during transportation and storage.



15973



19786

Example of JEDEC Standard JESD22-A112 level 2a label

FINAL PACKING

The sealed reel is packed into a cardboard box. A secondary cardboard box is used for shipping purposes.

RECOMMENDED METHOD OF STORAGE

Dry box storage is recommended as soon as the aluminum bag has been opened to prevent moisture absorption. The following conditions should be observed, if dry boxes are not available:

- Storage temperature 10 °C to 30 °C
- Storage humidity $\leq 60\%$ RH max.

After more than 672 h under these conditions moisture content will be too high for reflow soldering.

In case of moisture absorption, the devices will recover to the former condition by drying under the following condition:

192 h at $40^\circ\text{C} + 5^\circ\text{C}/-0^\circ\text{C}$ and < 5 % RH (dry air/nitrogen) or

96 h at $60^\circ\text{C} + 5^\circ\text{C}$ and < 5 % RH for all device containers or

24 h at $100^\circ\text{C} + 5^\circ\text{C}$ not suitable for reel or tubes.

An EIA JEDEC standard JESD22-A112 level 2a label is included on all dry bags.

ESD PRECAUTION

Proper storage and handling procedures should be followed to prevent ESD damage to the devices especially when they are removed from the antistatic shielding bag. Electro-static sensitive devices warning labels are on the packaging.

OZONE DEPLETING SUBSTANCES POLICY STATEMENT

It is the policy of Vishay Semiconductor GmbH to

1. Meet all present and future national and international statutory requirements.
2. Regularly and continuously improve the performance of our products, processes, distribution and operating systems with respect to their impact on the health and safety of our employees and the public, as well as their impact on the environment.

It is particular concern to control or eliminate releases of those substances into the atmosphere which are known as ozone depleting substances (ODSs).

The Montreal Protocol (1987) and its London Amendments (1990) intend to severely restrict the use of ODSs and forbid their use within the next ten years. Various national and international initiatives are pressing for an earlier ban on these substances.

Vishay Semiconductor GmbH has been able to use its policy of continuous improvements to eliminate the use of ODSs listed in the following documents.

1. Annex A, B and list of transitional substances of the Montreal Protocol and the London Amendments respectively.
2. Class I and II ozone depleting substances in the Clean Air Act Amendments of 1990 by the Environmental Protection Agency (EPA) in the USA.
3. Council Decision 88/540/EEC and 91/690/EEC Annex A, B and C (transitional substances) respectively.

Vishay Semiconductor GmbH can certify that our semiconductors are not manufactured with ozone depleting substances and do not contain such substances.

We reserve the right to make changes to improve technical design
and may do so without further notice.

Parameters can vary in different applications. All operating parameters must be validated for each customer application by the customer. Should the buyer use Vishay Semiconductors products for any unintended or unauthorized application, the buyer shall indemnify Vishay Semiconductors against all claims, costs, damages, and expenses, arising out of, directly or indirectly, any claim of personal damage, injury or death associated with such unintended or unauthorized use.

Vishay Semiconductor GmbH, P.O.B. 3535, D-74025 Heilbronn, Germany



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